

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
RYO HOSOI	03/04/2019
TAKASHI HONDA	03/11/2019
SEIICHI TAKAYAMA	03/11/2019
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SAE MAGNETICS (H.K.) LTD.
<b>Street Address:</b>	SAE TECHNOLOGY CENTRE, 6 SCIENCE PARK EAST AVENUE, HONG KONG SCIENCE PARK, SHATIN, N.T.
<b>City:</b>	HONG KONG
<b>State/Country:</b>	HONG KONG
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	16282383
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	SHIRAI-19005-USPT
<b>NAME OF SUBMITTER:</b>	CHARLES HO
<b>SIGNATURE:</b>	/Charles Ho/
<b>DATE SIGNED:</b>	03/13/2019
<b>Total Attachments: 3</b>	
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source=Executed assignment#page2.tif	
source=Executed assignment#page3.tif	

<b>ASSIGNMENT - Patent Application</b>		Docket Number: <b>SHIRAI-19005-USPT</b>
Whereas, the Assignor, comprising the following named inventors:		
ASSIGNOR(s)/ INVENTOR(s)	<b>Ryo Hosoi; Takashi Honda; and Seichi Takayama</b>	
made an invention entitled: <b><u>Light Source-Unit, Thermally Assisted Magnetic Head, Head Gimbal Assembly, and Hard Disk Drive</u></b>		
for which an application for Letters Patent of the United States: (Select one of the following):		
<input type="checkbox"/> is executed concurrently herewith		
<input checked="" type="checkbox"/> was filed in the U.S. Patent and Trademark Office on <u>02/22/2019</u>		
as U.S. Patent Application Serial No.: <u>16/282,383</u>		
ASSIGNEE (Full Name, Address and Country)	<b>SAE Magnetics (H.K.) Ltd.</b> <b>SAE Technology Centre, 6 Science Park East Avenue, Hong Kong Science Park, Shatin, N.T.</b> <b>Hong Kong</b>	
is desirous of acquiring our entire right, title and interest in and to said invention and the Letters Patent to be obtained therefor.		
<p>Now, therefore, in consideration of the payment by Assignee to Assignor of a sum corresponding to One Dollar (\$1.00), and for other good and valuable consideration, the receipt of which is hereby acknowledged, Assignor, intending to be legally bound, hereby sells, assigns and transfers to Assignee, its successors and assigns, the full and exclusive right, title and interest in and to said invention, all applications for Letters Patent for said invention, including all divisions, continuations, and continuations-in-part thereof, all rights to claim priority based thereon, and all Letters Patent, including reissues, to be obtained therefor, including any and all foreign patent rights in this invention corresponding thereto.</p> <p>Assignor hereby warrants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.</p> <p>Assignor agrees it shall be legally bound, upon request of the Assignee or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the Assignor has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the Assignee, and to execute all instruments proper to carry out the intent of this instrument.</p> <p>In witness whereof, this Assignment is executed on the day indicated below.</p>		

	Typed or Printed Name	Signature	Date
SIGNATURE	<u>Ryo Hosoi</u>	<u>X Ryo Hosoi</u>	<u>X Mar/4/2019</u>

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ASSIGNEE (Full Name, Address and Country)	<b>SAE Magnetics (H.K.) Ltd.</b>  <b>SAE Technology Centre, 6 Science Park East Avenue, Hong Kong Science Park, Shatin, N.T.</b>  <b>Hong Kong</b>	
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	Typed or Printed Name	Signature	Date
SIGNATURE	Takashi Honda	X <i>Takashi Honda</i>	X 3/11/19

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	Typed or Printed Name	Signature	Date
SIGNATURE	<b>Seichi Takayama</b>	<i>x Seichi Takayama</i>	<i>x Mar. 11, 2019</i>

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